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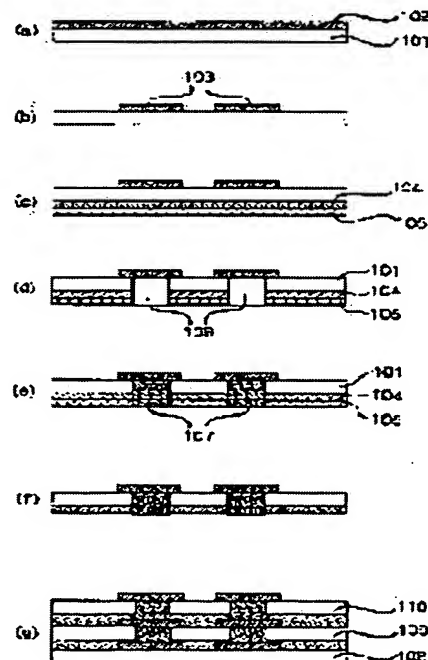
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(54) MANUFACTURE OF MULTILEVEL INTERCONNECTION BOARD AND MOUNTING METHOD OF ELECTRONIC COMPONENT BY USING THE MULTILEVEL INTERCONNECTION BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide the manufacturing method of a multilevel interconnection board which enables the improvement in the precision of a conductive paste filling position, without the use of an elaborate apparatus.

SOLUTION: An adhering material layer consisting of an adhesive layer 104 and a protective layer 105 which is removably provided on the adhesive layer 104 is laminated on the rear of a film substrate having circuit patterns. Via holes 106 which pierce through the film substrate and the adhering material layer are formed. A conductive paste is applied to the protective layer 5 to fill the via holes 106 with the conductive paste. After that, the protective layer 105 is removed from the adhesive layer 104.



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